

Title (en)  
Component cooling method

Title (de)  
Verfahren zur Kühlung eines Bauteils

Title (fr)  
Procédé de refroidissement d'un composant

Publication  
**EP 0640745 B1 19970423 (DE)**

Application  
**EP 94112390 A 19940809**

Priority  
DE 4328294 A 19930823

Abstract (en)  
[origin: EP0640745A1] In a method for the cooling of a thermally loaded component (1) with a plane outer wall (2), in which method, in a first cooling section (A) of the component (1) cooling air is fed through a cooling air feed (5) towards the outer wall (2) and is laterally deflected in front of the outer wall (2), and in a second cooling stage (B) is led further in a laterally connecting cooling air duct (3) for the purpose of further cooling parallel to the outer wall (2), homogenisation of the cooling is achieved in that, for reduction of the impact cooling in the first cooling section (A) the cooling air flow coming from the cooling air feed (5) is divided into a main flow and a bypass flow, the main flow is guided directly along the outer wall (2) of the component (1) to the cooling air duct (3), the bypass flow is guided to the cooling air duct (3) without any contact with the outer wall (2), and the two partial flows are brought together again at the inlet of the cooling air duct (3). <IMAGE>

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IPC 8 full level  
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